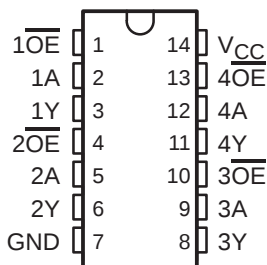


SN54LVTH125, SN74LVTH125 3.3-V ABT QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

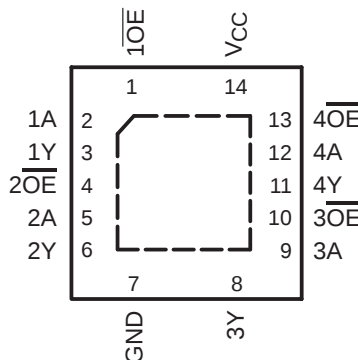
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- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

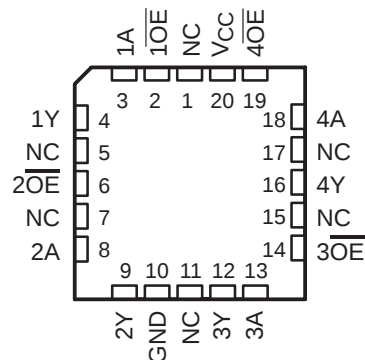
SN54LVTH125 . . . J OR W PACKAGE
SN74LVTH125 . . . D, DB, DGV, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVTH125 . . . RGY PACKAGE
(TOP VIEW)



SN54LVTH125 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These bus buffers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVTH125 devices feature independent line drivers with 3-state outputs. Each output is in the high-impedance state when the associated output-enable ($\overline{OE}$) input is high.

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74LVTH125RGYR	LXH125
	SOIC – D	Tube	SN74LVTH125D	LVTH125
		Tape and reel	SN74LVTH125DR	
	SOP – NS	Tape and reel	SN74LVTH125NSR	LVTH125
	SSOP – DB	Tape and reel	SN74LVTH125DBR	LXH125
	TSSOP – PW	Tube	SN74LVTH125PW	LXH125
		Tape and reel	SN74LVTH125PWR	
	TVSOP – DGV	Tape and reel	SN74LVTH125DGVR	LXH125
–55°C to 125°C	CDIP – J	Tube	SNJ54LVTH125J	SNJ54LVTH125J
	CFP – W	Tube	SNJ54LVTH125W	SNJ54LVTH125W
	LCCC – FK	Tube	SNJ54LVTH125FK	SNJ54LVTH125FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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SN54LVTH125, SN74LVTH125
3.3-V ABT QUADRUPLE BUS BUFFERS
WITH 3-STATE OUTPUTS

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description/ordering information (continued)

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

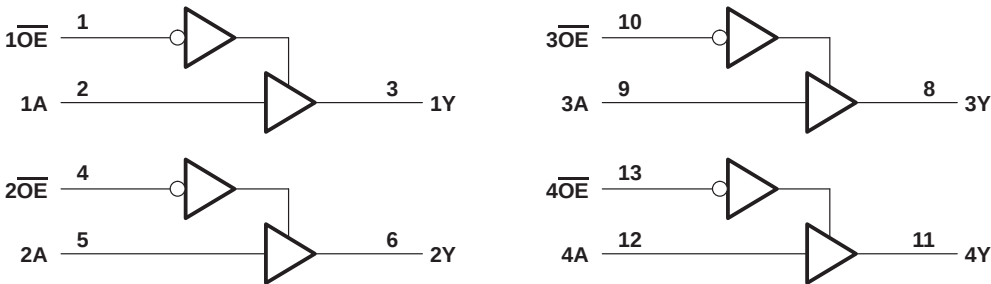
When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, RGY, and W packages.

SN54LVTH125, SN74LVTH125 3.3-V ABT QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O : SN54LVTH125	96 mA
SN74LVTH125	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVTH125	48 mA
SN74LVTH125	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.
4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

		SN54LVTH125		SN74LVTH125		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage		5.5		5.5	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 5: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54LVTH125, SN74LVTH125

3.3-V ABT QUADRUPLE BUS BUFFERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH125			SN74LVTH125			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}		V _{CC} = 2.7 V, I _I = -18 mA		-1.2			-1.2			V
V _{OH}		V _{CC} = 2.7 V to 3.6 V, I _{OH} = -100 μA		V _{CC} -0.2			V _{CC} -0.2			V
		V _{CC} = 2.7 V, I _{OH} = -8 mA		2.4			2.4			
		V _{CC} = 3 V		I _{OH} = -24 mA						
				I _{OH} = -32 mA			2			
V _{OL}		V _{CC} = 2.7 V		I _{OL} = 100 μA			0.2			V
				I _{OL} = 24 mA			0.5			
		V _{CC} = 3 V		I _{OL} = 16 mA			0.4			
				I _{OL} = 32 mA			0.5			
				I _{OL} = 48 mA			0.55			
				I _{OL} = 64 mA			0.55			
I _I		V _{CC} = 0 or 3.6 V, V _I = 5.5 V		10			10			μA
	Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND		±1			±1			
	Data inputs	V _{CC} = 3.6 V		V _I = V _{CC}			1			
				V _I = 0			-5			
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					±100			μA
I _I (hold)	Data inputs	V _{CC} = 3 V		V _I = 0.8 V		75		75		μA
				V _I = 2 V		-75		-75		
		V _{CC} = 3.6 V [‡] , V _I = 0 to 3.6 V						±500		
I _{OZH}		V _{CC} = 3.6 V, V _O = 3 V		5			5			μA
I _{OZL}		V _{CC} = 3.6 V, V _O = 0.5 V		-5			-5			μA
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE = don't care		±50*			±50			μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE = don't care		±50*			±50			μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND		Outputs high		0.12 0.19		0.12 0.19		mA
				Outputs low		4.5 7		4.5 7		
				Outputs disabled		0.12 0.19		0.12 0.19		
ΔI _{CC} [§]		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND		0.3			0.2			mA
C _i		V _I = 3 V or 0		4			4			pF
C _O		V _O = 3 V or 0		6.5			6.5			pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

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SN54LVTH125, SN74LVTH125 3.3-V ABT QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH125				SN74LVTH125				UNIT	
			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
t _{PLH}	A	Y	1	4.2		4.7	1	2	3.5		4.5	ns
t _{PHL}			1	4.1		5.1	1	2.1	3.9		4.9	
t _{PZH}	$\overline{\text{OE}}$	Y	1	4.9		5.6	1	2	4		5.5	ns
t _{PZL}			1.1	4.9		5.6	1.1	2.1	4		5.4	
t _{PHZ}	$\overline{\text{OE}}$	Y	1.5	5.3		5.9	1.5	2.3	4.5		5.7	ns
t _{PLZ}			1.3	4.7		4.2	1.3	2.8	4.5		4	

[†] All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

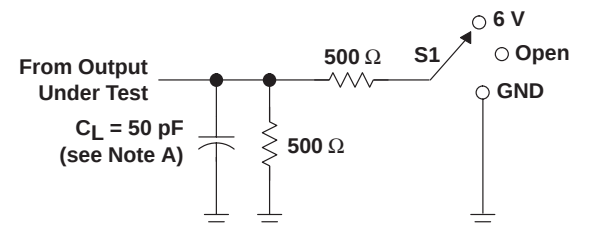
SN54LVTH125, SN74LVTH125

3.3-V ABT QUADRUPLE BUS BUFFERS

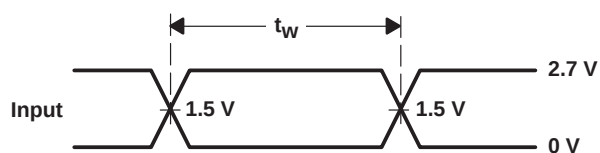
WITH 3-STATE OUTPUTS

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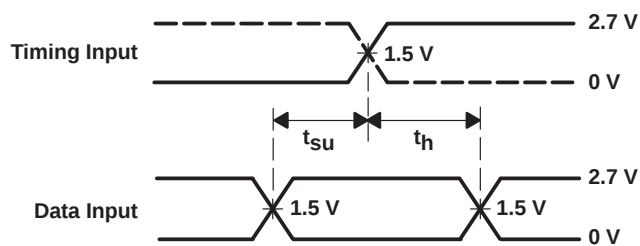
PARAMETER MEASUREMENT INFORMATION



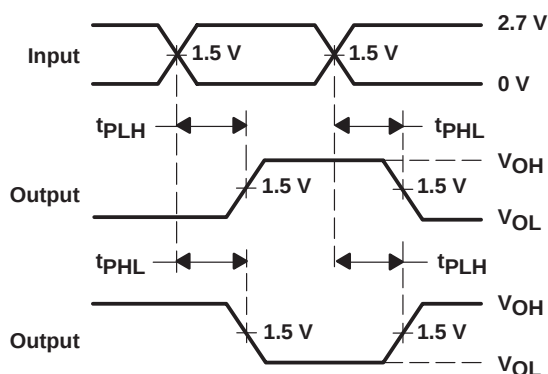
LOAD CIRCUIT



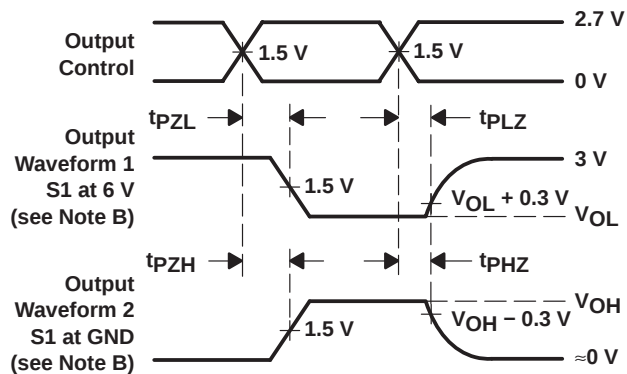
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

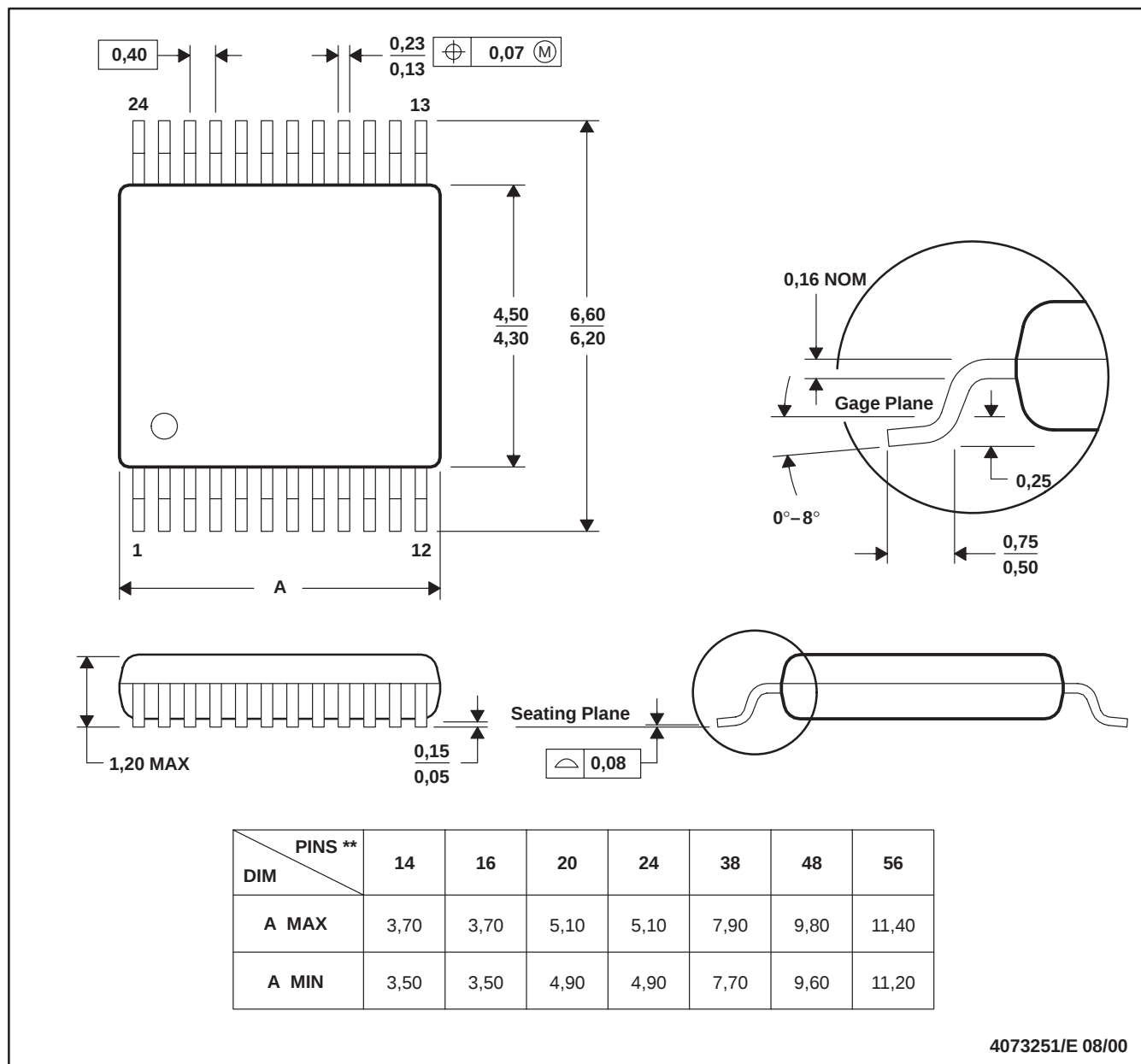
- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

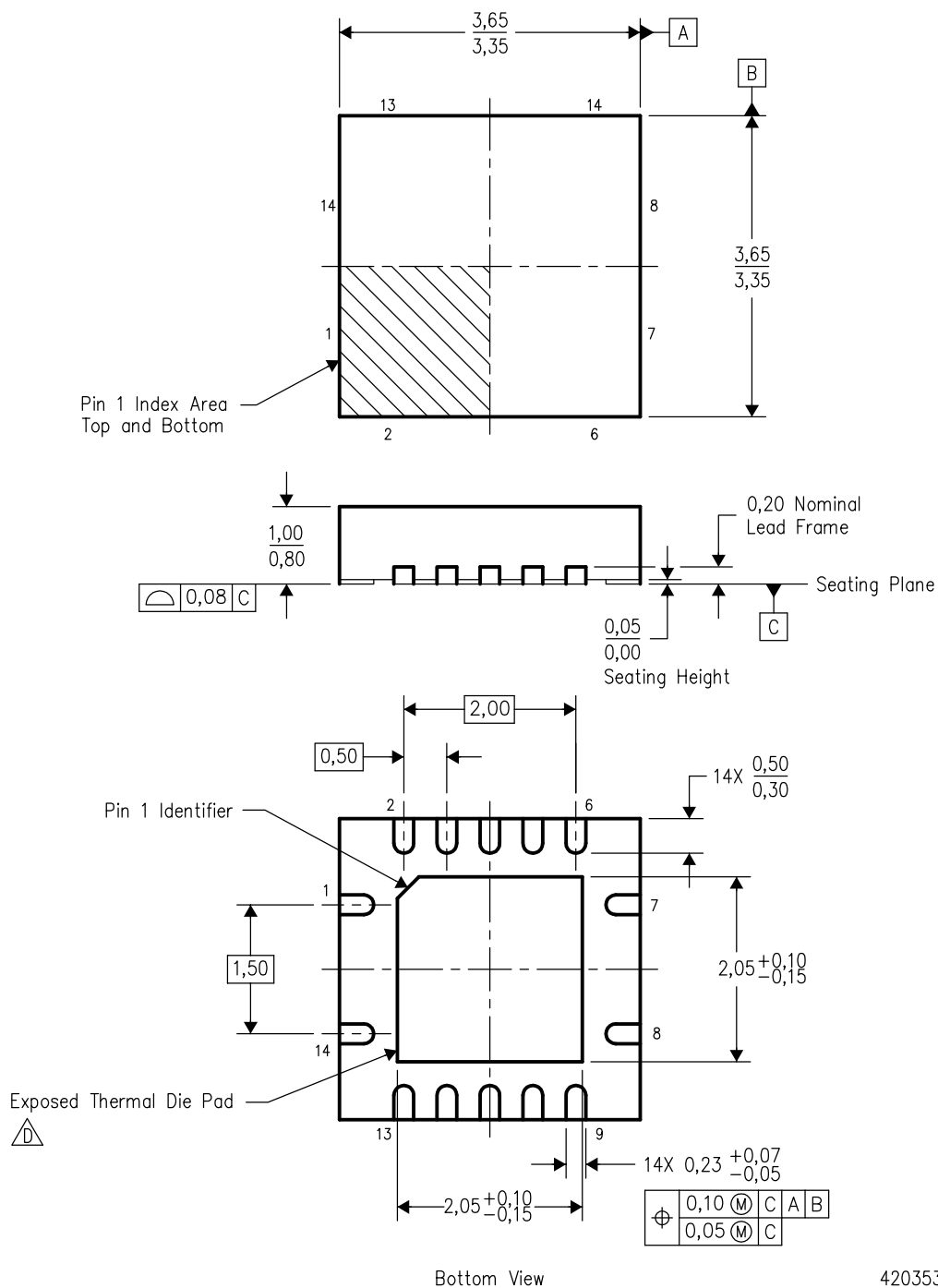
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK

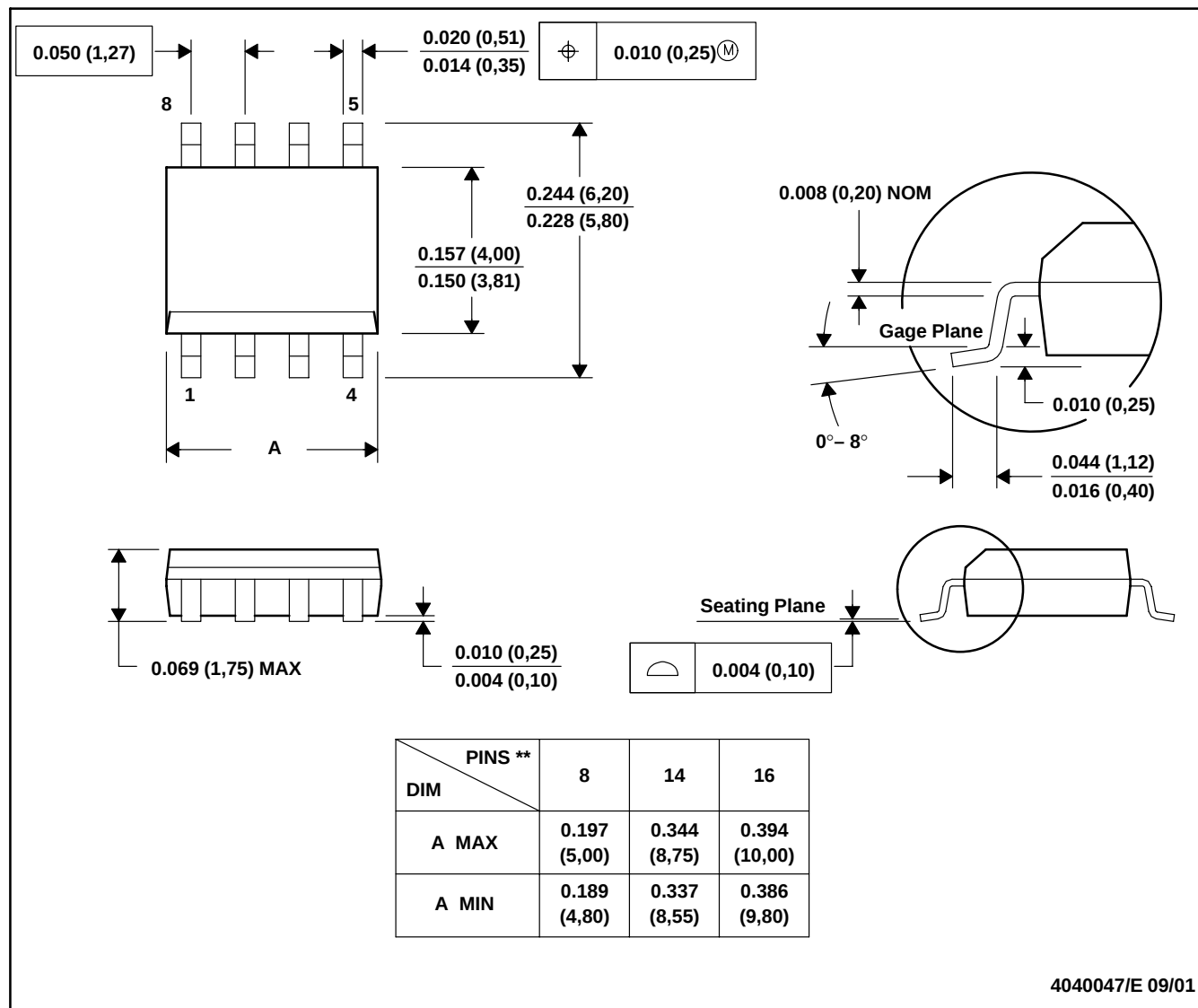


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 -  D. The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BA.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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